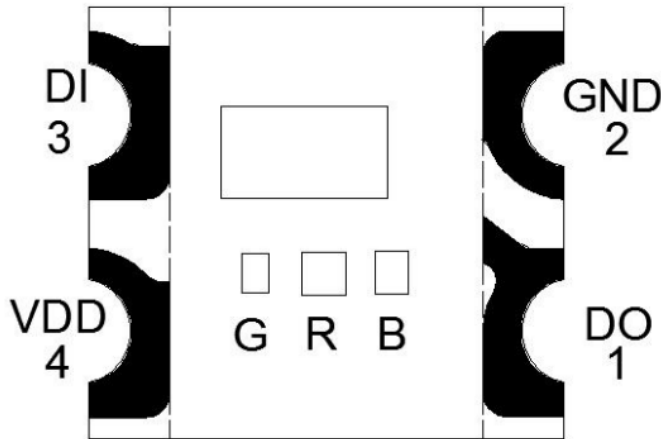


Layer Stack Legend

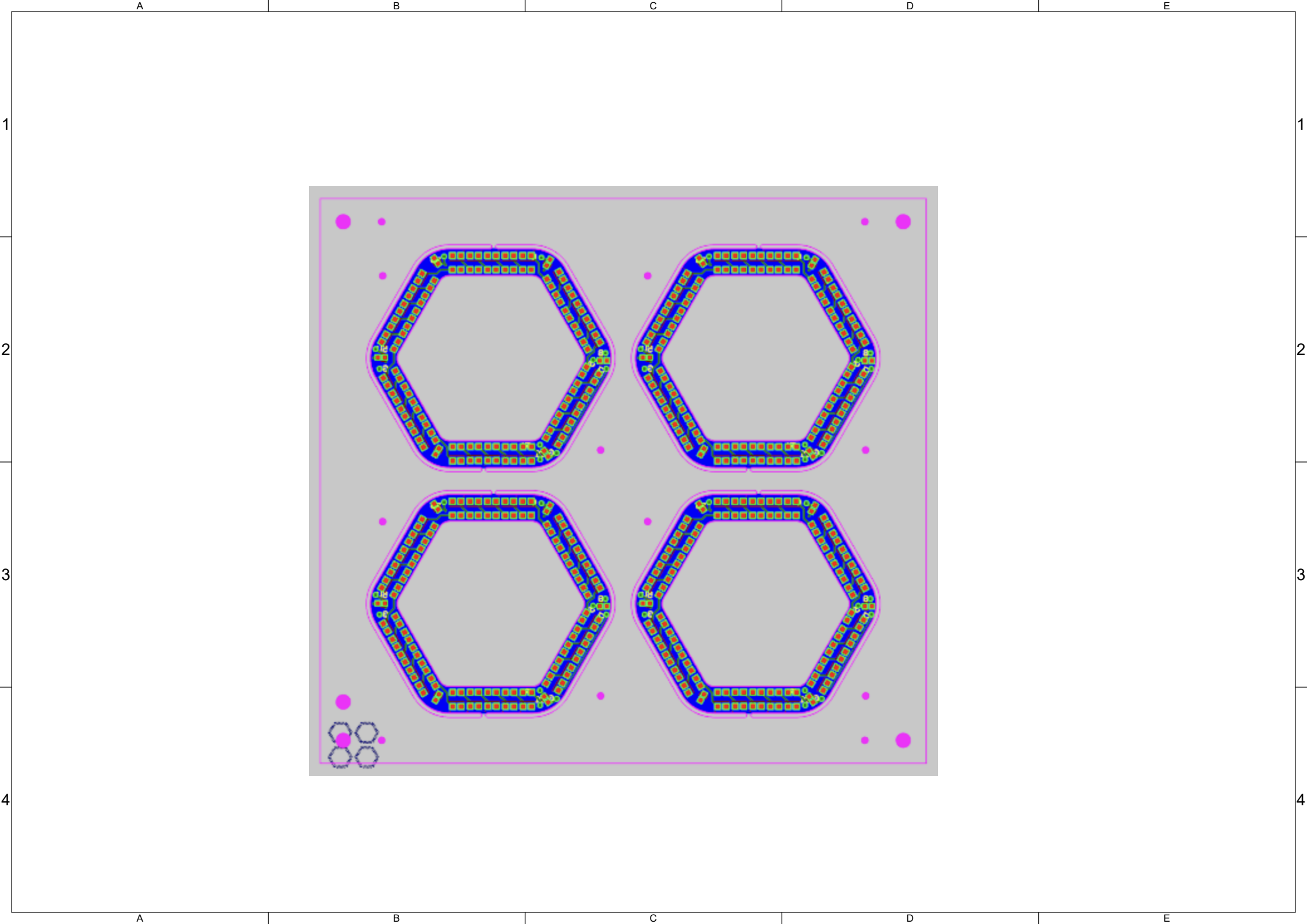
	Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Surface Material	Top Overlay	0.03mm	SM-002	Legend	GCT1
	PP-006	Top Coverlay	0.03mm		Solder Mask	
	Nickel, Gold	Adhesive 1	0.03mm		Adhesive	
		Top Surface Finish	0.01mm		Surface Finish	
	CF-004	Top Layer	0.02mm		Signal	GTL
	PP-006	Adhesive 2	0.02mm		Adhesive	
	<i>Prepreg</i>		<i>0.03mm</i>	<i>Composite dielectric</i>	<i>Dielectric</i>	
	PP-006	Adhesive 3	0.02mm		Adhesive	
	CF-004	Bottom Layer	0.02mm		Signal	GBL
	Nickel, Gold	Bottom Surface Finish	0.01mm		Surface Finish	
	PP-006	Adhesive 4	0.03mm		Adhesive	
	Surface Material	Bottom Solder	0.03mm	SM-002	Solder Mask	GCB1
	Core-009	Stiffener 1	0.10mm		Stiffener	
Board Layer Stack Bottom Overlay						Legend
Total thickness: 0.31mm						

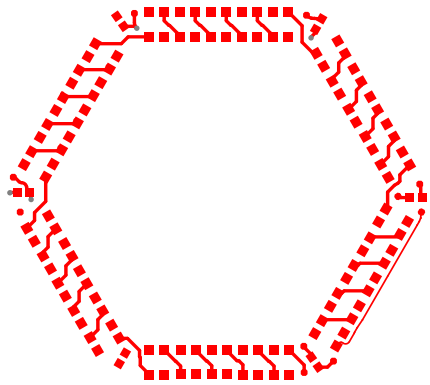
PIN Configuration



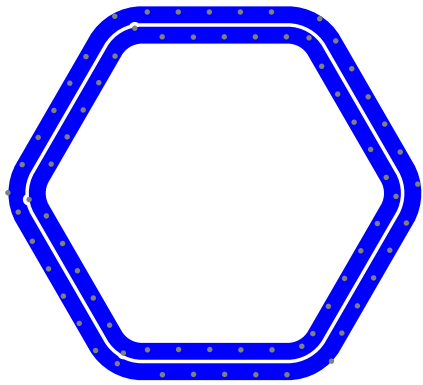
PIN Function

NO.	Symbol	PIN	Function description
1	DO	DATA OUT	Control data signal output
2	GND	GROUND	Ground, data & power grounding
3	DI	DATA IN	Control data signal input
4	VDD	POWER SUPPLY	Power supply



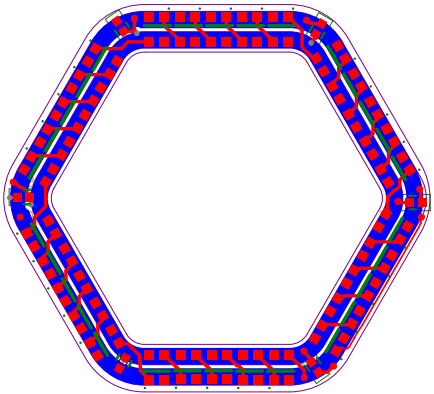


Top Layer



Bottom

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Coverlay	SM-002	0.025mm	4	
	Adhesive 1	PP-006	0.025mm	4.1	
	Top Surface Finish	Nickel, Gold	0.006mm		
1	Top Layer	CF-004	0.018mm		
	Adhesive 2	PP-006	0.020mm	4.1	
	PI 1	Composite dielectric	0.025mm	4.1	
	Adhesive 3	PP-006	0.020mm	4.1	
2	Bottom Layer	CF-004	0.018mm		
	Bottom Surface Finish	Nickel, Gold	0.006mm		
	Adhesive 4	PP-006	0.025mm	4.1	
	Bottom Solder	SM-002	0.025mm	4	
	Stiffener 1	Core-009	0.100mm	4.5	
	Board Layer Stack Bottom Overlay				



Top Layer
Bottom
Top Overlay
Bottom Overlay